
Chipsmall
深圳市津利帝科技有限公司
Geelead Technology Limited
Chipsmall
采购部

NOTES:

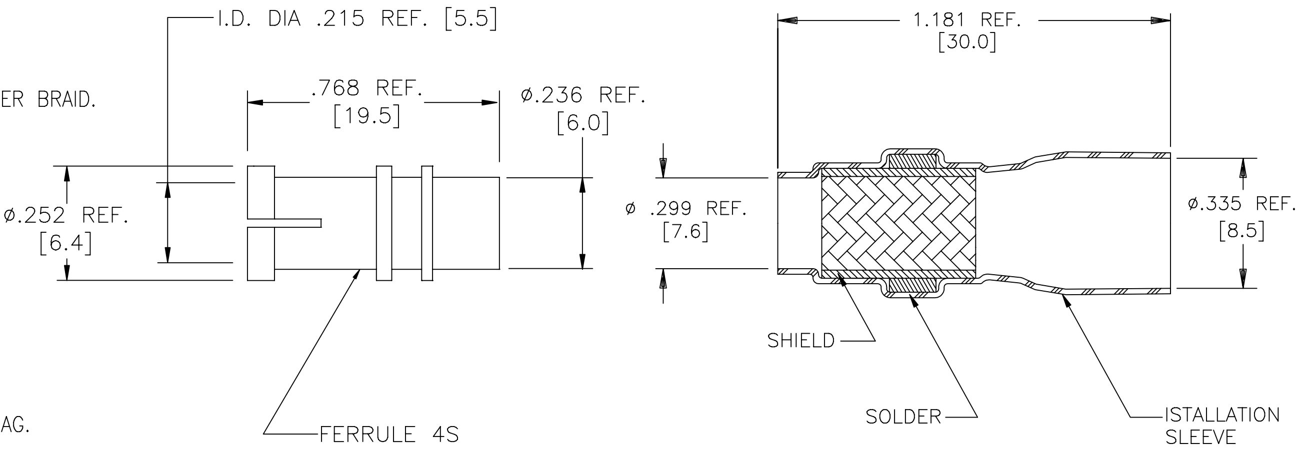
MATERIALS

1. FERRULE: COPPER ALLOY PER ASTM B139-95
2. INSULATION SLEEVE: HEAT-SHRINKABLE, TRANSPARENT BLUE, RADIATION CROSS-LINKED MODIFIED POLYVINYLIDENE FLUORIDE.
3. SOLDER PERFORM WITH FLUX:
   SOLDER: TYPE Sn63 PER ANSI-J-STD-006.
   FLUX: TYPE ROM1 PER ANSI-J-STD-004.
4. SHIELD: SOLDER IMPREGNATED, FLUX COATED, TIN PLATED COPPER BRAID.
   SOLDER: TYPE Sn63 PER ANSI-J-STD-006.
   FLUX: TYPE ROM1 PER ANSI-J-STD-004.
5. FINISH:
   A) FERRULE CADMIUM PLATED IN ACCORDANCE WITH QQ-P-416. OVER A SUITABLE UNDERPLATE.
6. INSTALLATION: SEE RAYCHEM INSTALLATION PROCEDURE RPIP-652-35.
7. PACKAGING: ONE SPIGOT AND ONE SOLDER SHIELD PER BAG. 10 BAGS IN A BOX.

8 THE VALUES TABLE GIVES GEOMETRICAL GUIDE LINES. HOWEVER PLATING, SHAPE, DIAMETER OF CABLES CAN BE VARY AND AN INSTALLATION MUST BE DONE TO GUARANTEE PROPER RESULT.

REVISIONS

LTR	DESCRIPTION	DATE	APPROVED
D	DRAWING HAS BEEN CONVERTED FROM FRENCH PER T-30412	12/10/2001	M.HIGGY

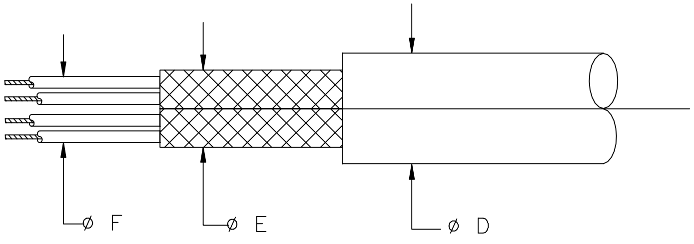


ø D OUTSIDE DIA OF JACKETS.		ø E OUTSIDE DIA OF BRAIDS.		ø F MAX. OUTSIDE DIA OF WIRES.
MIN.	MAX.	MIN.	MAX.	
.140 [3.55]	.315 [8.0]	.071 [1.8]	.236 [6.0]	.201 [5.1]

MAXIMUM QTY. OF BRAIDS: 4

8

APPLICATIONS



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SPECIFICATION CONTROL DRAWING

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. METRIC DIMENSIONS ARE IN BRACKETS.

DECIMALS
.XXX ± { mm}
.XX ± { mm}
ANGLES
.X ±

WEIGHT:

DRAWN	ZS.ORBAN	11/30/2001
CHECKED		
APPROVED	M.HIGGY	11/30/2001
RPN:		
CAD NAME	T30412.DWG	
THIRD ANGLE PROJECTION		

tyco/Electronics/Raychem
WIRE AND HARNESSING PRODUCTS
307 CONSTITUTION DRIVE
MENLO PARK, CALIFORNIA 94025

TITLE
SPIGOT LARGE SIZE WITH SOLDER SHIELD FOR MILTIPORT BACKHELL

SIZE	CODE IDENT. NO.	DWG. NO.	REV
C	06090	ECA-0030	D

DO NOT SCALE THIS DRAWING

SHEET 1 OF 1

SHEET 1
DWG NO. ECA-0030